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112935 U.S. PTO
11/646698

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies):

Jong H. Kim (12/20/2006)

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s): December 20, 2006

☒ Assignment ☐ Merger ☐ Change of Name☐ Security Agreement ☐ Joint Research Agreement☐ Government Interest Assignment☐ Executive Order 9424, Confirmatory License☐ Other

2. Name and address of receiving party(ies)

Name: HYNIX SEMICONDUCTOR INC.

Internal Address:

Street Address:

San 136-1, Ami-ri, Bubal-eup

City: Icheon-Si

State: Kyongki-do

Country: Republic of Korea Zip: 467-701

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application or patent number(s):

A. Patent Application No.(s)

This application

☒ This document is being filed together with a new application.

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: James P. Zeller
MARSHALL, GERSTEIN & BORUN LLP

Internal Address: Atty. Dkt.: 29936/43021

Street Address: 233 S. Wacker Drive, Suite 6300
Sears Tower

City: Chicago

State: IL Zip: 60606-6357

Phone Number: (312) 474-6300

Fax Number: (312) 474-0448

Email Address:

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

☐ Authorized to be charged by credit card☐ Authorized to be charged to deposit account☒ Enclosed☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers

Expiration Date

b. Deposit Account Number

Authorized User Name

9. Signature:

Signature

James P. Zeller 28,491

Name of Person Signing

December 28, 2006

Date

Total number of pages including cover sheet, attachments, and documents:

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the U.S. Postal Service as Express Mail, Airbill No. EL995019446US, on the date shown below in an envelope addressed to: MS Assignment Recordation Services, Director of the US Patent and Trademark Office, P.O. Box 1450, Alexandria, VA 22313-1450.

Dated: December 28, 2006

Signature: Salvador Raigosa (Salvador Raigosa)

PATENT

REEL: 018749 FRAME: 0174

01/03/2007 JBALIAN 00000004 11646698

04 FD:502

(40.00 US)

ASSIGNMENT

Serial No:

Filed:

Title: METAL LAYER STRUCTURE OF SEMICONDUCTOR DEVICE

For \$10.00 (Ten Dollars) and other good and sufficient consideration, the receipt and sufficiency whereof are hereby acknowledged, the undersigned hereby assign to Hynix Semiconductor Inc., of San 136-1, Ami-ri, Bubal-eub, Icheon-si, Kyoungki-do, Republic of Korea, (hereinafter "Assignee"), its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, executed by the undersigned on, _____ and in said application and any and all other applications, both United States and foreign, which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States and foreign countries, which may be obtained on any of said applications, and in any reissue or extension thereof.

The undersigned hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignee.

The undersigned hereby authorize and request the attorneys of record in said application to insert in this assignment the execution date and/or filing date and serial number of said application when officially known.

The undersigned warrant themselves to be the owners of the interest herein assigned and to have the right to make this assignment and further warrant that there are no outstanding prior assignments, licenses, or other rights in the interest herein assigned.

For said consideration the undersigned hereby agree, upon the request and at the expense of said assignee, its successors and assigns, to execute any and all divisional, continuation, continuation-in-part and substitute applications for said invention or improvements, and any necessary oath or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon said application, and any and all applications and other documents for Letters Patent in foreign countries on said invention or improvements, that said assignee, its successors or assigns, may deem necessary or expedient, and for the aforesaid consideration the undersigned further agree upon the request of said assignee, its successors or assigns, in the event of any application or Letters Patent assigned herein becoming involved in Interference, to cooperate to the best of the ability of the undersigned with said assignee, its successors or assigns, in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof, the undersigned hereby agreeing to perform, upon request, any and all affirmative acts to obtain said Letters Patent, both United States and foreign, and vest all rights therein hereby conveyed in said assignee, its successors and assigns, whereby said Letters Patent will be held and enjoyed by said assignee, its successors and assigns, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

Date: December 20, 2006

Signature: _____

Name: Long Hoon KIM

Date: _____

Signature: _____

Name: _____

Date: _____

Signature: _____

Name: _____

Date: _____

Signature: _____

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